

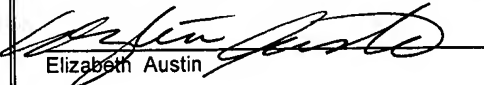
IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: **Sean Michael Malolepszy, et al.**  
Serial No.: **TBD**  
Filed: **Herewith**  
For: **Bond Surface Conditioning System For  
Improved Bondability**

Docket No.: **TI-33434.1**  
Examiner: **TBD**  
Art Unit.: **TBD**  
Conf. No.: **TBD**

**TRANSMITTAL OF FORMAL DRAWINGS**

Commissioner For Patents  
Attn: Official Drafts Person  
Alexandria, VA 22313-1450

<b>MAILING CERTIFICATE UNDER 37 C.F.R. § 1.8(a)</b>	
I hereby certify that the above correspondence is being deposited with the U.S. Postal Service as First Class Mail in an envelope addressed to: Commissioner For Patents, Alexandria, VA 22313-1450.	
 Elizabeth Austin	<u>7/1/2003</u> Date

Dear Sir:

Submitted herewith are 5 sheets of formal drawings.

The enclosed drawings are being provided in a timely manner therefore no additional fee is required.

Texas Instruments Incorporated  
P. O. Box 655474, MS 3999  
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Respectfully submitted,



Michael K. Skrehot  
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